PCN Number: 202		211208000.1			PCN Date:		:	December 13, 2021		
Title: Qualification of DM			IOS6 as an additional Fab site option for select LBC8 devices							
Customer	Contact:		PCN Manager			Dept:			Quality Services	
Proposed 1 st Ship Date:			Mar13, 2022		Estimated Sample Availability:		Date provided at sample request.			
Change Type:										
Assembly Site			Assembly Process			Assembly Materials				
Design			Electrical Specification				Mechanical Specification			
Test Site				Packing/Shipping/Labeling		ng	Test Process		Process	
☐ Wafer Bump Site			Wafer Bump Material			Wafer Bump Process		er Bump Process		
			Wafer Fab Materials				Wafer Fab Process			
				Part number change						
PCN Details										

PCN Details

Description of Change:

Texas Instruments is pleased to announce the qualification of its DMOS6 fabrication facility as an additional Wafer Fab source for the selected devices listed in the "Product Affected" section.

С	urrent Fab Site	е	Additional Fab Site		
Current Fab Site	Process	Wafer Diameter	New Fab Site	Process	Wafer Diameter
RFAB	LBC8	300mm	DMOS6	LBC8	300mm

Qual details are provided in the Qual Data Section.

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Changes to product identification resulting from this PCN:

Fab Site Information:

Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City
RFAB	RFB	USA	Richardson
DMOS6	DM6	USA	Dallas

Sample product shipping label (not actual product label)



(L)T0:3750



(1P) SN74LS07NSR (D) 0336 31T)LOT: 3959047MLA 4W) TKY(1T) 7523483S12 (V) 0033317 (21L) CCO:USA (20L) CSO: SHE

Product Affected:

LP8758A2B4YFFR	LP8758A2E2YFFR	LP8758A2EAYFFR	LP8758A2F0YFFR
LP8758A2C5YFFR	58A2C5YFFR LP8758A2E3YFFR		

Qualification Report

Approve Date 30-Jun-2016

Qualification Results Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name / Condition	Duration	Qual Device: P8758A2EAYFFR	QBS Product Reference: <u>P8758A1YFFR</u>	QBS Process Reference: <u>TAS2555YZ</u>	QBS Process Reference: TA S2553YFF
AC	Autoclave 121C	96/hrs @ 121C	-	3/231/0	-	-
HTOL	Life Test 125C	1000 Hours	-	3/231/0	3/231/0	3/231/0
HTSL	High Temp Storage Bake 150C	1000/hrs @ 150C	-	3/231/0		-
TC	Temperature Cycle -55/125	700 Cycles	-	3/231/0	3/231/0	-
тнв	Biased Temperature and Humidity, 85C/85%RH	1000/hrs @85C/85%	-	3/231/0		-
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	3/231/0	-
ELFR	Early Life Failure Rate, 125C	48 Hours	-	-	-	3/3000/0
НВМ	ESD - HBM	2500 V	1/3/0	-	-	-
CDM	ESD - CDM	1000 V	1/3/0	-	-	-
LU	Latch-up	(per JESD78) 25C	1/6/0	-	-	-
LU	Latch-up	(per JESD78) 85C	1/6/0	-	-	-
LU	Latch-up	(per JESD78) 125C	1/6/0	-	-	-
ED	Electrical Characterization	Per Datasheet Limits	1/Pass	-	-	-
SBS	Bump Shear	-	-	-	3/108/0	-

- QBS: Qual By Similarity. Product Family is qualified at LEVEL2-260C
- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free (SMT) and Green

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